

SOT1152-1

plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; resin based

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN32R
Package type industry code	HVQFN32R
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	R (resin based)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	16-11-2009

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	0.75	-	0.8	0.9	mm
e	nominal pitch	-	-	0.65	-	mm
n ₂	actual quantity of termination	-	-	32	-	

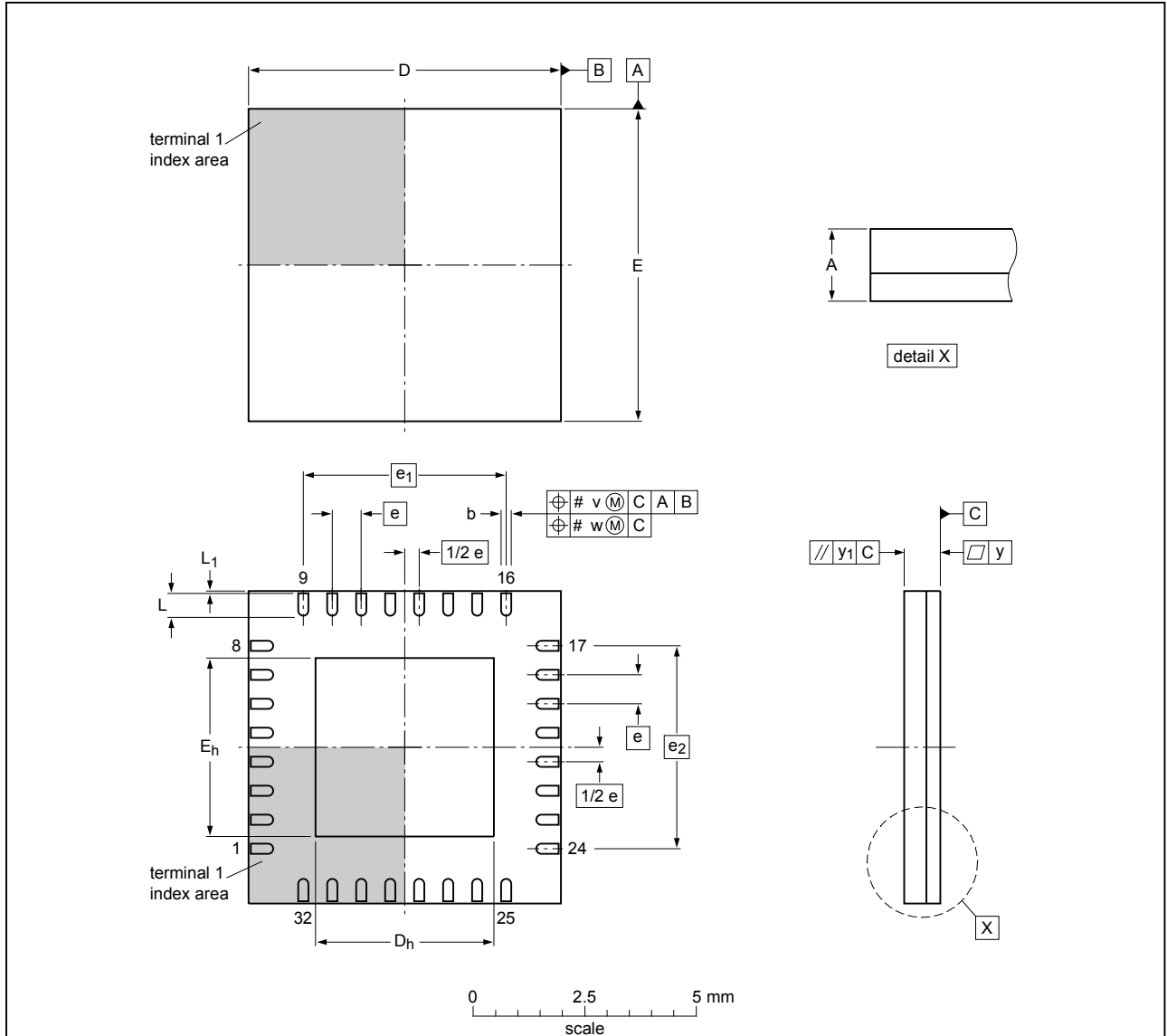


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2. Package outline

HVQFN32R: plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; resin based; body 7 x 7 x 0.8 mm

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Dimensions

Unit	A	b	D	D _h	E	E _h	e	e ₁	e ₂	L	L ₁	v	w	y	y ₁
max	0.90	0.28	7.1	4.05	7.1	4.05				0.55	0.10				
mm nom	0.80	0.23	7.0	4.00	7.0	4.00	0.65	4.55	4.55	0.50	0.05	0.1	0.05	0.08	0.1
min	0.75	0.18	6.9	3.95	6.9	3.95				0.45	0.00				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included

sot1152-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1152-1	---	---	---		09-10-13 09-11-16

Fig. 1. Package outline HVQFN32R (SOT1152-1)

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3. Legal information

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